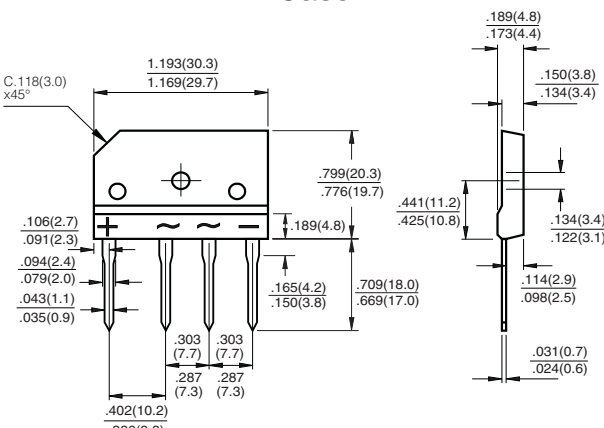



**5.0 Amp. Glass Passivated Bridge Rectifier**

<p style="text-align: center;"><b>Plastic Case</b></p>  <ul style="list-style-type: none"> <li>• <b>Mounting Instructions</b></li> <li>• High temperature soldering guaranteed: 260 °C – 10 sc.</li> <li>• Recommended mounting torque: 0.8 N.m.</li> </ul>	<p><b>Voltage</b> 200 to 600 V</p> <p><b>Current</b> 5.0 A</p>  <ul style="list-style-type: none"> <li>• <b>Glass Passivated Junction Chips.</b></li> <li>• Lead and polarity identifications.</li> <li>• Case: Molded Plastic.</li> <li>• Ideal for printed circuit board (P.C.B.).</li> <li>• High surge current capability.</li> <li>• The plastic material carries U/L recognition 94 V-O.</li> </ul>
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**Maximum Ratings, according to IEC publication No. 134**

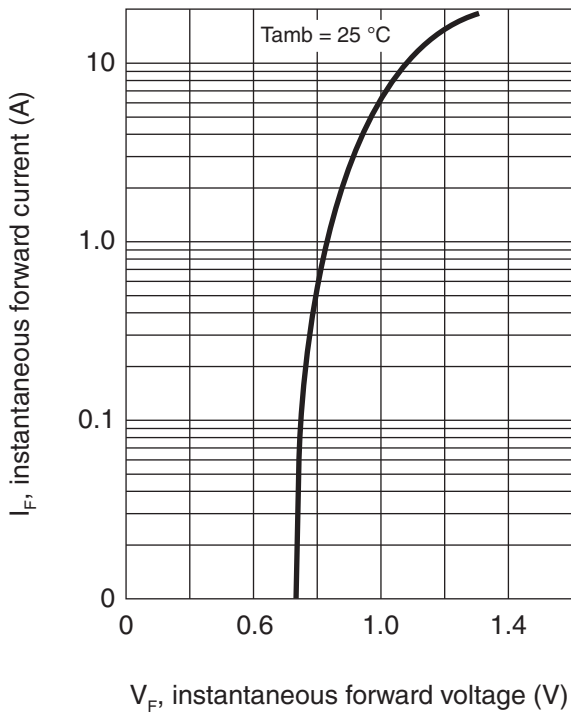
		<b>D5.1XB 20</b>	<b>D5.1XB 30</b>	<b>D5.1XB 60</b>
$V_{RRM}$	Peak recurrent reverse voltage (V)	200	300	600
$V_{RMS}$	Maximum RMS Voltage (V)	140	210	420
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	5.0 A at $T_c: 100\text{ }^\circ\text{C}$ 3.0 A at $25\text{ }^\circ\text{C}$		
$I_{FSM}$	8.3 ms. Peak Forward Surge Current (Jedec Method)	180 A		
$V_{DIS}$	Dielectric strength (terminals to case, AC 1 min.)	2500 V		
$I^2t$	$I^2t$ value for fusing ( $t = <8.3\text{ ms}$ )	120 A <sup>2</sup> sec		
$T_j$	Operating temperature range	-40 to +150 °C		
$T_{stg}$	Storage temperature range	-40 to +150 °C		

**Electrical Characteristics at  $T_{amb} = 25\text{ }^\circ\text{C}$**

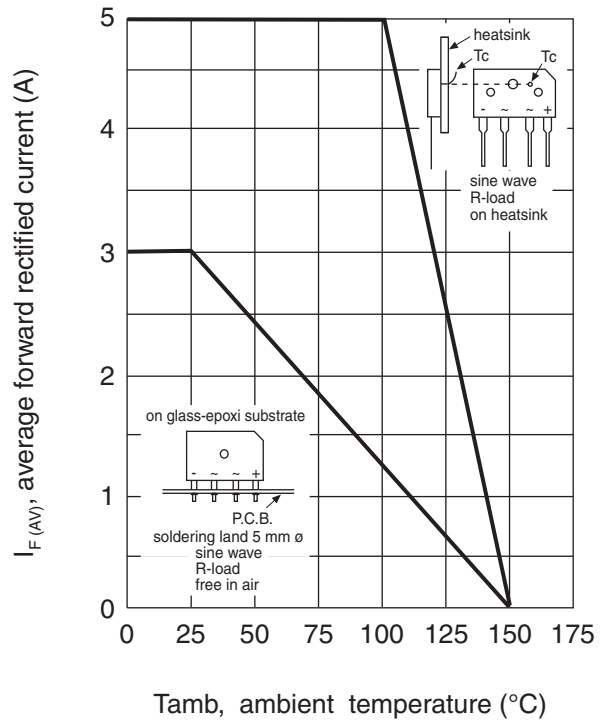
$V_F$	Max. forward voltage drop per diode at $I_F = 4.0\text{ A}$ $I_F = 8.0\text{ A}$	1.00 V 1.10 V
$I_R$	Max. instantaneous reverse current at $V_{RRM}$	5 $\mu\text{A}$
$R_{th(j-c)}$ $R_{th(j-a)}$	MAXIMUM THERMAL RESISTANCE Junction-case. With Heatsink. Junction-Ambient. Without Heatsink.	3.4 °C/W 22 °C/W

**Rating And Characteristic Curves**

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

